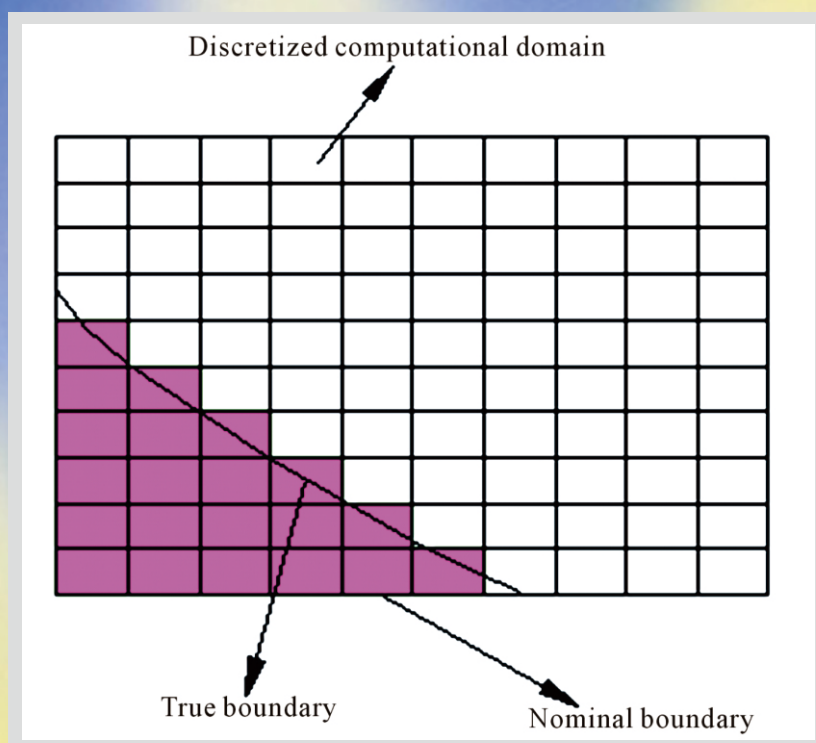


# Journal of Electronics Cooling and Thermal Control



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The figure on the front cover is from the article published in *Journal of Electronics Cooling and Thermal Control*, 2012, Vol. 2, No. 4, pp. 53-61 by Asad Bahrami, Seyyed Abdolreza Gandjalikhan Nassab and Maliheh Hashemipour.

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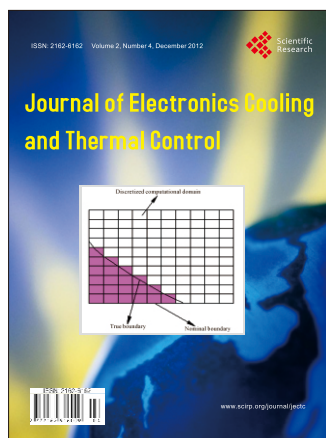
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**Journal of Electronics Cooling and Thermal Control (JECTC)** is a quarterly, peer-reviewed, academic journal. It aims to provide a vehicle for the exchange and dissemination of original research results, technical notes, and state-of-the-art reviews pertaining to the electronic cooling and thermal system control technology in the computer and electronics industries.

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